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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









350mW, SMD Switching Diode

FEATURES

- · Designed for mounting on small surface
- Low Capacitance
- Low forward voltage drop
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- On-board DC/DC converter

MECHANICAL DATA

- Case: SOT-23
- Molding compound meets UL 94 V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Packing code with suffix "G" means green compound (halogen-free)
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- · Polarity: Indicated by cathode band
- Weight: 8 mg (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I _{F(AV)}	200	mA		
V_{RRM}	100	V		
I _{FSM}	2	Α		
V _F at I _F =10mA	1	V		
T _J Max.	150	°C		
Package	SOT-23			
Configuration	Single dice			





PARAMETER			SYMBOL	PART NUMBER	UNIT
	MMBD	04148		5D	
Manking and an the device	MMBD	04148CA		A1	
Marking code on the device	MMBD	04148CC		A4	
	MMBD	04148SE		A7	
Repetitive peak reverse voltage			V_{RRM}	75	V
Forward current			I _{F(AV)}	200	mA
Repetitive peak forward surge current			I _{FRM}	700	mA
Non-repetitive peak forward surge current at t=1µs at t=1s		I _{FSM}	2	А	
			1		
Junction temperature range			T _J	-55 to +150	°C
Storage temperature range			T _{STG}	-55 to +150	°C

1



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	357	°C/W	

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS SYMBO		MIN	MAX	UNIT	
Forward voltage per diode (1)	I _F = 10mA, T _J = 25°C	V _F	-	1.0	V	
	V _R =20V ,T _J = 25°C		-	25.0	nA	
Reverse current @ rated V _R per diode ⁽²⁾	V _R =75V ,T _J = 25°C	I _R	-	5.0	μΑ	
	V _R =20V ,T _A = 150°C		-	50.0		
Devenue has aladoune voltana	$I_R=5\mu A , T_J=25^{\circ}C$	V	75	-	V	
Reverse breakdown voltage	I _R =100μA ,T _J = 25°C	$V_{(BR)}$	100	-		
Junction capacitance	1 MHz, V _R =0V	CJ	-	4.0	pF	
Reverse recovery time	$I_F=10mA, I_R=1mA,$ $R_L=100\Omega, V_R=6V$	t _{rr}	-	4.0	ns	

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION				
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
MMBD414X	RF	G	SOT-23	3K / 7" Reel
(Note 1&2)	R5	G		10K / 13" Reel

Notes:

- 1. Whole series with green compound
- 2. "XX" is Device code from "8" to "8SE".

EXAMPLE				
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
MMBD4148 RFG	MMBD4148	RF	G	Green compound

2



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig. 1 Power Derating Curve

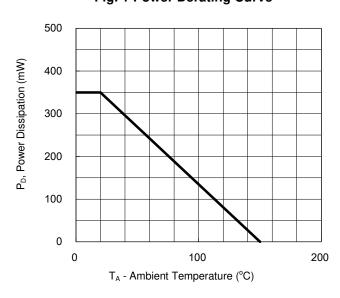


Fig.2 Forward Characteristics

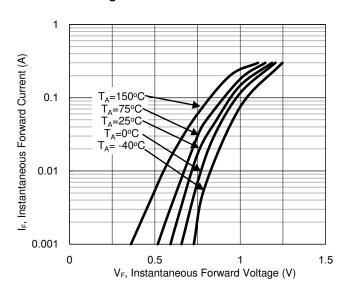


Fig.3 Typical Reverse Characteristics

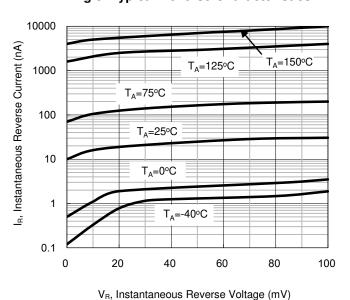
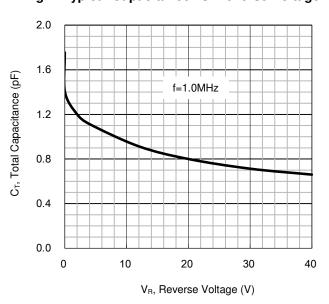


Fig.4 Typical Capacitance vs. Reverse Voltage



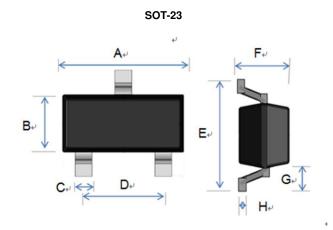
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3



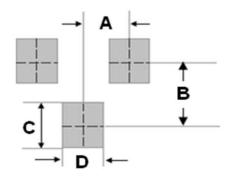


PACKAGE OUTLINE DIMENSION



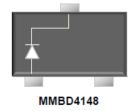
DIM. Unit		(mm)	Unit(inch)	
DIW.	Min	Max	Min	Max
Α	2.70	3.10	0.106	0.122
В	1.10	1.50	0.043	0.059
С	0.30	0.51	0.012	0.020
D	1.78	2.04	0.070	0.080
Е	2.10	2.64	0.083	0.104
F	0.89	1.30	0.035	0.051
G	0.55 REF		0.022	REF
Н	0.10 REF		0.004	REF

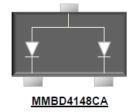
SUGGEST PAD LAYOUT

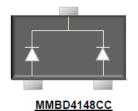


DIM.	Unit(mm)	Unit(inch)
	ТҮР	TYP
Α	0.95	0.037
В	2.00	0.079
С	0.90	0.035
D	0.80	0.031

PIN CONFIGURATION







MMBD4148SE



Taiwan Semiconductor

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